

IEEE 26th INTERNATIONAL SYMPOSIUM ON THE PHYSICAL AND FAILURE ANALYSIS OF INTEGRATED CIRCUITS

- IPFA 2019 -

02 – 05 July 2019

Grand Hyatt Hotel, Hangzhou, China

6th December 2018

Dear IPFA Supporter

IPFA 2019 EXHIBITION

We are pleased to invite you to participate in the IPFA 2019 Exhibition to be held from 2 to 5 July 2019 at Grand Hyatt Hotel, Hangzhou, China. The exhibition is held in conjunction with the 26th International Symposium on the Physical and Failure Analysis of Integrated Circuits (IPFA 2019). IPFA 2019 is organized by the IEEE RS/ EPS/ EDS Singapore Chapter, IEEE Electron Devices Society Hangzhou Chapter. The Symposium is technically co-sponsored by the IEEE Electron Device Society and IEEE Reliability Society.

The Symposium will be devoted to the fundamental understanding of the physical mechanisms governing failure in a large variety of advanced semiconductor devices and the electrical-physical failure analysis techniques.

Both the Symposium and the Exhibition are established events and are expected to draw over 250 participants from around the world who have specific interests in Integrated Circuit Reliability and Failure Analysis. As such, IPFA 2019 Exhibition will be an excellent opportunity for your company to reach out to the professionals in the field and promote your equipment and products to the Failure Analysis community in the semiconductor and electronics industries.

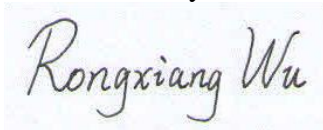
The cost of a standard shell scheme booth (3m x 3m) for the exhibition period is 4,600 USD and the 2m x 2m shell scheme booth will cost 3,200 USD. This includes one night stay at the Grand Hyatt Hotel, Hangzhou, one complimentary registration (2 registrations for 3m x 3m booths) for the symposium from 03 to 05 July 2019. There will be a 10% discount for early registration with full payment before **28 February 2019**.

We are pleased to enclose the following for your information and perusal:

1. Exhibition Information
2. Proposed Exhibition Layout Plan
3. Perspective View of Shell Scheme Booth
4. IPFA 2019 1st Call for Papers

Please book your exhibition space by **28 February 2019** with full payment to **IEEE IPFA 2019**, to take advantage of the early bird discount. Please contact the Exhibition Chair if you require more information.

Yours sincerely



Rongxiang Wu
Exhibitions/Sponsorship Chair

ORGANIZED BY:



Reliability / Electronics Packaging /
Electron Devices Singapore Chapter

TECHNICALLY CO-SPONSORED BY:



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